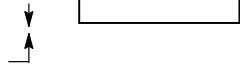
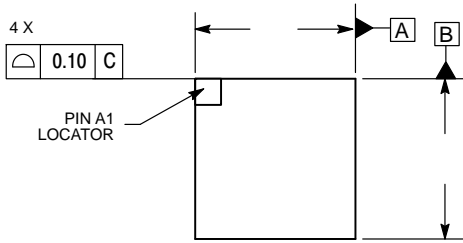
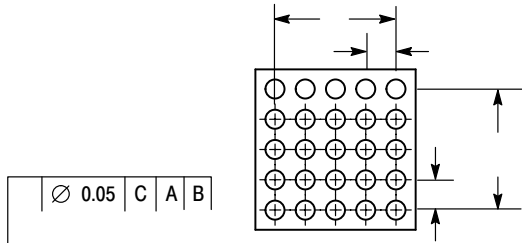


FLIP iCHIP i25 CSP
CASE 499G i01
ISSUE B

DATE 03 MAY 2005



SEATING
PLANE



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	iii	0.700
A1		
A2	0.380	0.430
D	2.650 BSC	
E		
b	0.290	0.340
e	0.500 BSC	
D1	2.000 BSC	
E1	2.000 BSC	